INTERFERENCE SEARCH

Ref #	Hits	Search Query	DBs	Default Operat or	Plural s	Time Stamp
L9	14	((bond or Bump) and wire and (rais\$6 or mov\$3) and (head or tool or capillar\$6) and horizontal and (direction or side or turn or position)).clm.	US-PGPU B	OR	ON	2005/11/21 12:03
L17	1	(wire and (bump or ball) and (capillary and opposite and horizontal and direction and movement)). clm.	US-PGPU B	OR	ON	2005/11/21 12:11
L18	1	(first with bump with flat with portion with capillary). clm.	US-PGPU B	OR	ON	2005/11/21 12:12
L20	1	(rais\$3 with mov\$3 with capillary with horizontal with direction).clm.	US-PGPU B	OR-	ON	2005/11/21 12:13
L21	1	(first with conductor with perfom\$3 secondary with bond\$3 with surface with second with conductor). clm.	US-PGPU B	OR	ON	2005/11/21 12:15
L22	2	(wire and bump and ball and capillary and opposite and horizontal and direction and rais\$3).clm.	US-PGPU B	OR	ON	2005/11/21 12:20
L24	1 .	(wire and bump and ball and capillary and opposite and horizontal and direction and rais\$3 and inclin\$3 and wedge and orient\$3 and opposite and side and first and conductor).clm.	US-PGPU B	OR	ON	2005/11/21 12:23
L25	1	(wire and bump and ball and capillary and horizontal and direction and rais\$3 and inclin\$3 and wedge and opposite and side and first and conductor).clm.	US-PGPU B	OR	ON	2005/11/21 12:24

Search History 11/21/2005 12:27:07 PM Page 1 C:\Documents and Settings\maboagye\My Documents\EAST\Workspaces\10781189 wire bonding.amend.update 10-11-2005.wsp

L26	1	(wire and bump and ball and capillary and horizontal and direction and rais\$3 and wedge and opposite and side and first and conductor).clm.	US-PGPU B	OR	ON	2005/11/21 12:24
L27	1	(wire and bump and capillary and horizontal and direction and rais\$3 and wedge and opposite and side and first and conductor).clm.	US-PGPU B	OR	ON	2005/11/21 12:25
L28	1	(wire and bump and capillary and horizontal and direction and rais\$3 and wedge and first and conductor).clm.	US-PGPU B	OR	ON	2005/11/21 12:25
L29	1	(wire and bump and capillary and horizontal and direction and rais\$3 and wedge).clm.	US-PGPU B	OR	ON	2005/11/21 12:25
L30	3	(wire and bump and capillary and horizontal and direction and rais\$3).clm.	US-PGPU B	OR	ON	2005/11/21 12:26

Ref #	Hits	Search Query	DBs	Default Operat or	Plural s	Time Stamp
L1	147	257/673.ccls.	US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/21 11:28
L2	1052	257/676.ccls.	US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/21 11:31
L3	19	2 and capillary	US-PGPU B; EPO;	OR	ON	2005/11/21 11:32
			JPO; DERWEN T; IBM_TDB			
L4	169	2 and wire and (multiple or plurality or tripple or double) with (bump or ball or bond\$3)	US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/21 11:40
L5	1 2	(2 or 1) and wire and (rais\$6 or mov\$3) with (head or tool or capillar\$6) and horizontal with (direction or side or turn or position)	US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/21 11:43
L6	2507	wire and (rais\$6 or mov\$3) with (head or tool or capillar\$6) and horizontal with (direction or side or turn or position)	US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/21 11:44
L7	82	wire with (rais\$6 or mov\$3) with (head or tool or capillar\$6) with horizontal with (direction or side or turn or position)	US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/21 11:44

S1	1000	228/180.5.ccls.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/21 11:26
S2	1421	228/4.5.ccls.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/11 15:30
S4	975	228/175.ccls.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/11 15:32
S 5	1211	228/180-22.ccls.	US-PGPU B; USPAT; USOCR;= EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/11 15:32
S6	3617	S1 or S2 or S3 or S4	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/11 15:32

S7	508	S6 and Wire near50 pass\$3 cappillary near50 (ball or bump)near50 (join\$3 or bond\$3) near50 (conductor or substrate) near50 (rais\$3 or move or lower) near50 (horizontal or vertical) near50 side near50 flat near50 portion near50 press\$3	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/11 15:39
S8	18	("0509019" "3986255" "4661192" "4750666" "4875617" "4875618" "4889274" "5090609"). PN. OR ("5186381"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/10/11 15:59
S9	1	"20040152292"	US-PGPU B; USPAT	OR	ON	2005/11/20 14:10
S10	0	("2004/0152292").URPN.	USPAT	OR	ON	2005/11/20 14:27
S12	937	228/180.5.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/20 14:29
S13	1367	-228/4.5 ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ΘN	2005/11/20 15:34
S14	2	S13 and bump same capillary same flat same portion	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/20 15:35

S15	35	S13 and bump same capillary	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM TDB	OR	ON	2005/11/20 15:37
S16	2567	438/612.ccls.	US-PGPU	OR	ON	2005/11/20
			B; USPAT; EPO; JPO; DERWEN			15:38
			T; IBM_TDB			
S17	1360	438/613.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/20 15:38
S18	3455	S16 or S17	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/20 15:38
S19	98	S18 and bump same capillary	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/20 15:42
S20	2048	257/737.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/20 15:41

S21	2277	257/773.ccls.	US-PGPU	OR	ON	2005/11/20
021		2017170.0010.	В;	3	•••	15:41
			USPAT;			
			EPO; JPO;			
			DERWEN			
			T;			
			IBM_TDB			
S22	4206	S20 or S21	US-PGPU	OR	ON	2005/11/20 15:42
			B; USPAT;			15.42
			EPO;			
			JPO;			
			DERWEN T;			
			IBM_TDB			
S23	111	S22 and bump same	US-PGPU	OR	ON	2005/11/20
		capillary	B;			15:45
			USPAT; EPO;			
			JPO;			
		·	DERWEN			
			T; IBM_TDB			
S24	68	bump and capillary and	US-PGPU	OR	ON	2005/11/20
024	00	(lower\$3 or rais\$3 or	B;			15:47
*:		mov\$3) and horizontal and	USPAT;	-		
		flat near50 portion and press\$3 near50 bond\$3	USOCR; EPO;			
	Fa	hiessas liegion nolidas	JPO;			
			DERWEN			
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